

Kester Launches NP560 Solder Paste

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Kester is proud to announce the launch of NP560, a no-clean, lead-free, halogen-free solder paste. It consistently delivers paste transfer efficiencies of 0.50 to 0.55 AR and is fully capable of printing and reflowing 01005 components, even in air, with minimal graping behavior. In addition to its stable, consistent product performance, NP560 has redefined the voiding standard for PCB assembly and has the potential for low voiding performance.

For additional information on this product including technical and safety data sheets, please visit <u>https://www.kester.com/products/product/np560-solder-paste</u>.

For any questions or additional information, please contact: Fil Marcial-Hatfield, Global Product Manager at <u>fmarcial@kester.com</u>.

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Kester is a global supplier of assembly materials for the Electronic Assembly and Semiconductor Packaging industries. Kester is focused on delivering innovative, robust and high-quality solutions to help our customers address their technological challenges. Kester's current product portfolio includes soldering attachment materials such as solder paste, soldering chemicals, TSF (tacky solder flux) materials, and metal products such as bar, solid and flux-cored wire. Kester is an Illinois Tool Works (ITW) company. ITW is a Fortune 200 company that produces engineered fasteners and components, equipment and consumable systems, and specialty products. It employs approximately 49,000 people, and is based in Glenview, Illinois, with operations in 57 countries.